

Thermal Expansion in a MEMS Device

Introduction

The purpose of this model is to exemplify the use of the Material Library in COMSOL Multiphysics. This library contains more than 20,000 property functions for over 2600 materials. The larger part of these properties are mechanical and thermal properties for solid materials given as functions of temperature. You need the Material Library to build the model.

The example also shows how to set up a model of thermal expansion when the structure is constrained.

Note: This model requires the Material Library.

Thermal expansion is a common method used in the microscale to displace a part of a component, for example in an actuator.

Model Definition

The figure below shows the model geometry:



Figure 1: Geometry of the device.

The model consists of two sets of physics:

- A thermal balance with a heat source in the device, originating from Joule heating (ohmic heating). Air cooling is applied on the boundaries except at the position where the device is attached to a circuit board, where a thermal insulation condition is set.
- A force balance for the structural analysis with a volume load caused by thermal expansions. The device is fixed at the positions where it is attached to a circuit board (see Figure 1). The effect of possible thermal expansion for the circuit board is investigated.

The device is made of the copper-beryllium alloy UNS C17500, and the circuit board is made of FR4 material.

The thermal balance consists of a balance of flux at steady state. The heat flux is given by conduction only. The heat source is a constant heat source of $1 \cdot 10^8 \text{ W/m}^3$. The air cooling at the boundaries is expressed using a constant heat transfer coefficient of 10 W/m² and an ambient temperature of 298 K.

The expression for thermal expansion requires a strain reference temperature for the copper-beryllium alloy, which in this case is 298 K.

All other thermal and mechanical properties are obtained from the Material Library.

Results and Discussion

The following figure shows the temperature distribution in the device. The heat source increases the temperature to around 323.67 K from an ambient temperature of 298 K. The temperature varies less than 1/100 of a degree in the device.



Figure 2: Temperature field in the device. The edges of the original geometry are shown in black. The deformed shape is exaggerated by a factor of 200.

The following figures show the stress field in the deformed device with fully constrained attachment boundaries (Figure 3), and with the expansion effect taken into account for the circuit board (Figure 4). The latter case leads to certain relaxation of the constraint applied to the device boundaries attached to the board. The resulting maximum von Mises stress becomes less by an order of magnitude. The stress is well within the elastic region for the material.

Surface: von Mises stress (MPa) Max/Min Volume: Displacement magnitude (µm)



Figure 3: The von Mises stress in the deformed structure with fully constrained attachment boundaries. The edges of the original geometry are shown in black. The deformed shape is exaggerated by a factor of 200.

Surface: von Mises stress (MPa) Max/Min Volume: Displacement magnitude (µm)



Figure 4: The von Mises stress in the deformed structure when the circuit board thermal expansion effect is modeled. The deformed shape is exaggerated by a factor of 200.

Application Library path: MEMS_Module/Sensors/thermal_expansion

Modeling Instructions

From the File menu, choose New.

NEW

In the New window, click Model Wizard.

MODEL WIZARD

- I In the Model Wizard window, click 间 3D.
- 2 In the Select Physics tree, select Structural Mechanics>Thermal-Structure Interaction> Thermal Stress, Solid.
- 3 Click Add.
- 4 Click 🔿 Study.
- 5 In the Select Study tree, select General Studies>Stationary.
- 6 Click M Done.

GEOMETRY I

- I In the Model Builder window, under Component I (compl) click Geometry I.
- 2 In the Settings window for Geometry, locate the Units section.
- 3 From the Length unit list, choose µm.

Work Plane I (wp1)

- I In the Geometry toolbar, click 📥 Work Plane.
- 2 In the Settings window for Work Plane, click 📥 Show Work Plane.

Work Plane I (wpI)>Plane Geometry

In the Model Builder window, click Plane Geometry.

Work Plane I (wp1)>Rectangle I (r1)

- I In the Work Plane toolbar, click Rectangle.
- 2 In the Settings window for Rectangle, locate the Size and Shape section.
- 3 In the Width text field, type 10.
- 4 In the **Height** text field, type 80.

- 5 Locate the Position section. In the xw text field, type -100.
- 6 In the Work Plane toolbar, click 🟢 Build All.

Work Plane I (wp1)>Copy I (copy1)

- I In the Work Plane toolbar, click 💭 Transforms and choose Copy.
- 2 Select the object rI only.
- 3 In the Settings window for Copy, locate the Displacement section.
- 4 In the **xw** text field, type 30.
- 5 In the Work Plane toolbar, click 📳 Build All.

Work Plane I (wp1)>Circle I (c1)

- I In the Work Plane toolbar, click 🕑 Circle.
- 2 In the Settings window for Circle, locate the Size and Shape section.
- 3 In the Radius text field, type 10.
- 4 Locate the Position section. In the xw text field, type -80.
- 5 In the **yw** text field, type 80.
- 6 In the Work Plane toolbar, click 🟢 Build All.

Work Plane 1 (wp1)>Circle 2 (c2)

- I In the Work Plane toolbar, click 🕑 Circle.
- 2 In the Settings window for Circle, locate the Size and Shape section.
- 3 In the Radius text field, type 20.
- 4 Locate the **Position** section. In the **xw** text field, type -80.
- **5** In the **yw** text field, type 80.
- 6 In the Work Plane toolbar, click 🟢 Build All.

Work Plane 1 (wp1)>Rectangle 2 (r2)

- I In the Work Plane toolbar, click Rectangle.
- 2 In the Settings window for Rectangle, locate the Size and Shape section.
- 3 In the Width text field, type 40.
- 4 In the **Height** text field, type 20.
- 5 Locate the Position section. In the xw text field, type -100.
- 6 In the **yw** text field, type 60.
- 7 In the Work Plane toolbar, click 📗 Build All.



Work Plane I (wp1)>Difference I (dif1)

- I In the Work Plane toolbar, click 🛑 Booleans and Partitions and choose Difference.
- 2 Select the object c2 only.
- 3 In the Settings window for Difference, locate the Difference section.
- 4 Find the Objects to subtract subsection. Select the 🔲 Activate Selection toggle button.
- **5** Select the objects **c1** and **r2** only.



Work Plane I (wp1)>Array I (arr1)

- I In the Work Plane toolbar, click 💭 Transforms and choose Array.
- 2 Click in the Graphics window and then press Ctrl+A to select all objects.
- 3 In the Settings window for Array, locate the Size section.
- 4 In the **xw size** text field, type 4.
- 5 Locate the **Displacement** section. In the **xw** text field, type 50.
- 6 In the Work Plane toolbar, click 🏢 Build All.



Work Plane 1 (wp1)>Rectangle 3 (r3)

- I In the Work Plane toolbar, click Rectangle.
- 2 In the Settings window for Rectangle, locate the Size and Shape section.
- 3 In the Width text field, type 30.
- **4** In the **Height** text field, type 10.
- 5 Locate the Position section. In the xw text field, type -70.
- 6 In the Work Plane toolbar, click 🟢 Build All.

Work Plane I (wpI)>Array 2 (arr2)

- I In the Work Plane toolbar, click 💭 Transforms and choose Array.
- 2 Select the object r3 only.
- 3 In the Settings window for Array, locate the Size section.
- 4 In the **xw size** text field, type 3.
- 5 Locate the **Displacement** section. In the **xw** text field, type 50.



Extrude I (extI)

- In the Model Builder window, under Component I (compl)>Geometry I right-click
 Work Plane I (wpl) and choose Extrude.
- 2 In the Settings window for Extrude, locate the Distances section.
- **3** In the table, enter the following settings:

Distances (µm)

10

4 Click 🟢 Build All Objects.

Form Union (fin)

- I In the Model Builder window, click Form Union (fin).
- 2 In the Settings window for Form Union/Assembly, click 📗 Build Selected.

3 Click the **Graphics** toolbar.



Next, create selections for use when defining the boundary conditions.

DEFINITIONS

Fixed

- I In the **Definitions** toolbar, click **The Box**.
- 2 In the Settings window for Box, type Fixed in the Label text field.
- 3 Locate the Geometric Entity Level section. From the Level list, choose Boundary.
- 4 Locate the **Box Limits** section. In the **y maximum** text field, type 1[um].

5 Locate the Output Entities section. From the Include entity if list, choose Entity inside box.



Heat Flux

- I In the Definitions toolbar, click 🍡 Complement.
- 2 In the Settings window for Complement, type Heat Flux in the Label text field.
- 3 Locate the Geometric Entity Level section. From the Level list, choose Boundary.
- 4 Locate the Input Entities section. Under Selections to invert, click + Add.
- 5 In the Add dialog box, select Fixed in the Selections to invert list.

6 Click OK.



Тор

- I In the **Definitions** toolbar, click **The Box**.
- 2 In the Settings window for Box, type Top in the Label text field.
- **3** Locate the **Geometric Entity Level** section. From the **Level** list, choose **Boundary**.
- 4 Locate the **Box Limits** section. In the **z minimum** text field, type 1 [um].

5 Locate the Output Entities section. From the Include entity if list, choose Entity inside box.



ADD MATERIAL

I In the Home toolbar, click 🙀 Add Material to open the Add Material window.

- 2 Go to the Add Material window.
- 3 In the tree, select Material Library>Copper Alloys>UNS C17500>UNS C17500 [solid].
- 4 Click Add to Component in the window toolbar.
- 5 In the Home toolbar, click 🙀 Add Material to close the Add Material window.

MATERIALS

UNS CI7500 [solid] (mat1)

- I In the Settings window for Material, locate the Material Contents section.
- 2 In the table, enter the following settings:

Property	Variable	Value	Unit	Property group
Poisson's ratio	nu	0.34	1	Young's modulus and Poisson's ratio

MULTIPHYSICS

Thermal Expansion 1 (tel)

- I In the Model Builder window, under Component I (compl)>Multiphysics click Thermal Expansion I (tel).
- 2 In the Settings window for Thermal Expansion, locate the Model Input section.
- 3 Click **Go to Source**.

GLOBAL DEFINITIONS

Default Model Inputs

- I In the Model Builder window, under Global Definitions click Default Model Inputs.
- 2 In the Settings window for Default Model Inputs, locate the Browse Model Inputs section.
- 3 Find the Expression for remaining selection subsection. In the Volume reference temperature text field, type 298[K].

SOLID MECHANICS (SOLID)

Fixed Constraint I

- I In the Model Builder window, under Component I (compl) right-click Solid Mechanics (solid) and choose Fixed Constraint.
- 2 In the Settings window for Fixed Constraint, locate the Boundary Selection section.
- **3** From the **Selection** list, choose **Fixed**.

HEAT TRANSFER IN SOLIDS (HT)

In the Model Builder window, under Component I (compl) click Heat Transfer in Solids (ht).

Heat Source 1

- I In the Physics toolbar, click 🔚 Domains and choose Heat Source.
- 2 In the Settings window for Heat Source, locate the Domain Selection section.
- 3 From the Selection list, choose All domains.
- **4** Locate the **Heat Source** section. In the Q_0 text field, type 1e8.

Heat Flux 1

- I In the Physics toolbar, click 🔚 Boundaries and choose Heat Flux.
- 2 In the Settings window for Heat Flux, locate the Boundary Selection section.
- 3 From the Selection list, choose Heat Flux.
- 4 Locate the Heat Flux section. Click the Convective heat flux button.

- **5** In the h text field, type 10.
- **6** In the T_{ext} text field, type 298.

MESH I

Mapped I

- I In the Mesh toolbar, click \bigwedge Boundary and choose Mapped.
- 2 In the Settings window for Mapped, locate the Boundary Selection section.
- **3** From the **Selection** list, choose **Top**.

Size I

- I Right-click Mapped I and choose Size.
- 2 In the Settings window for Size, locate the Element Size section.
- 3 From the Predefined list, choose Extremely fine.
- 4 Click 📗 Build All.

Swept I

In the Mesh toolbar, click A Swept.

Distribution I

- I Right-click Swept I and choose Distribution.
- 2 In the Settings window for Distribution, locate the Distribution section.
- 3 In the Number of elements text field, type 3.
- 4 Click 📗 Build All.
- **5** Click the **Comextents** button in the **Graphics** toolbar.

FIXED BOARD

- I In the Model Builder window, click Study I.
- 2 In the Settings window for Study, type Fixed Board in the Label text field.
- **3** In the **Home** toolbar, click **= Compute**.

RESULTS

Stress (solid)

The first default plot shows the von Mises stress in the deformed material. Add markers to show the minimum and maximum displacement, and adjust the deformation scaling to reproduce the plot shown in Figure 3.

Surface 1

- I In the Model Builder window, expand the Stress (solid) node, then click Surface I.
- 2 In the Settings window for Surface, locate the Expression section.
- 3 From the Unit list, choose MPa.

Stress (solid)

In the Model Builder window, click Stress (solid).

Max/Min Volume 1

- I In the Stress (solid) toolbar, click 间 More Plots and choose Max/Min Volume.
- 2 In the Settings window for Max/Min Volume, locate the Coloring and Style section.
- 3 From the Color list, choose Red.

Deformation

- I In the Model Builder window, expand the Results>Stress (solid)>Surface I node, then click Deformation.
- 2 In the Settings window for Deformation, locate the Scale section.
- **3** Select the **Scale factor** check box.
- 4 In the associated text field, type 200.
- 5 In the Stress (solid) toolbar, click 🗿 Plot.
- 6 Click the $\sqrt{-}$ Go to Default View button in the Graphics toolbar.

Temperature (ht)

The second default plots shows the temperature field that should be similar to that displayed in Figure 2.

- I In the Model Builder window, click Temperature (ht).
- 2 In the Settings window for 3D Plot Group, click to expand the Number Format section.
- 3 Select the Manual color legend settings check box.
- 4 In the **Precision** text field, type 6.

5 In the Temperature (ht) toolbar, click **O** Plot.



Next include the thermal expansion effect for the circuit board. Add another material to represent it.

ADD MATERIAL

- I In the Home toolbar, click 🙀 Add Material to open the Add Material window.
- 2 Go to the Add Material window.
- 3 In the tree, select Built-in>FR4 (Circuit Board).
- 4 Click 间 Add to Component I (compl).
- 5 In the Home toolbar, click 🙀 Add Material to close the Add Material window.

MATERIALS

- FR4 (Circuit Board) (mat2)
- I In the Settings window for Material, locate the Geometric Entity Selection section.
- 2 From the Geometric entity level list, choose Boundary.
- 3 From the Selection list, choose Fixed.

SOLID MECHANICS (SOLID)

Fixed Constraint I

In the Model Builder window, under Component I (comp1)>Solid Mechanics (solid) click Fixed Constraint I.

Thermal Expansion 1

- I In the Physics toolbar, click 📃 Attributes and choose Thermal Expansion.
- 2 In the Settings window for Thermal Expansion, locate the Boundary Selection section.
- 3 From the Selection list, choose Fixed.
- **4** Locate the **Thermal Expansion Properties** section. In the *T* text field, type **solid**.T.
- **5** In the T_{ref} text field, type 298[K].

Add a second study for computation with board thermal expansion.

ADD STUDY

- I In the Home toolbar, click $\stackrel{\sim}{\sim}$ Add Study to open the Add Study window.
- 2 Go to the Add Study window.
- 3 Find the Studies subsection. In the Select Study tree, select General Studies>Stationary.
- 4 Click Add Study in the window toolbar.
- 5 In the Home toolbar, click ~ 2 Add Study to close the Add Study window.

EXPANDED BOARD

- I In the Model Builder window, click Study 2.
- 2 In the Settings window for Study, type Expanded Board in the Label text field.
- 3 Locate the Study Settings section. Clear the Generate default plots check box.
- **4** In the **Home** toolbar, click **= Compute**.

Group and duplicate the existing plots, then set them to the newly created dataset.

RESULTS

Isothermal Contours (ht), Stress (solid), Temperature (ht)

- I In the Model Builder window, under Results, Ctrl-click to select Stress (solid), Temperature (ht), and Isothermal Contours (ht).
- 2 Right-click and choose Group.

Fixed Board

In the Settings window for Group, type Fixed Board in the Label text field.

Expanded Board

- I Right-click Fixed Board and choose Duplicate.
- 2 In the Model Builder window, click Fixed Board I.
- 3 In the Settings window for Group, type Expanded Board in the Label text field.

Stress (solid) 1

- I In the Model Builder window, click Stress (solid) I.
- 2 In the Settings window for 3D Plot Group, locate the Data section.
- 3 From the Dataset list, choose Expanded Board/Solution 2 (sol2).
- 4 In the Stress (solid) I toolbar, click **I** Plot.

The computed stress field and deformation should be similar to that shown in Figure 4.

Temperature (ht) I

- I In the Model Builder window, click Temperature (ht) I.
- 2 In the Settings window for 3D Plot Group, locate the Data section.
- 3 From the Dataset list, choose Expanded Board/Solution 2 (sol2).

Isothermal Contours (ht) I

- I In the Model Builder window, click Isothermal Contours (ht) I.
- 2 In the Settings window for 3D Plot Group, locate the Data section.
- 3 From the Dataset list, choose Expanded Board/Solution 2 (sol2).

Finally, disable the circuit board thermal expansion in the first study, so that you can compute the fixed configuration again.

FIXED BOARD

Step 1: Stationary

- I In the Model Builder window, expand the Fixed Board node, then click Step 1: Stationary.
- 2 In the Settings window for Stationary, locate the Physics and Variables Selection section.
- **3** Select the Modify model configuration for study step check box.
- 4 In the Physics and variables selection tree, select Component I (compl)> Solid Mechanics (solid)>Fixed Constraint I>Thermal Expansion I.
- 5 Click 💋 Disable.